

客户 CUSTOMER:

日期 DATE:

# 纳入仕様书 SPECIFICATION

产品名称 PRODUCT NAME: Diplexer

贵司料号 YOUR PART NO.:

敝司料号 OUR PART NO.: MDPX21M0917P69-D25

版本号 VERSION.: V1.1

接受 RECEPTION

THE SPECIFICATION HAS BEEN ACCEPTED.

该纳入仕様书已被我司接受

日期:  
DATE:

公司:  
COMPANY:

批准  
CFMD

审核  
CHKD

接收  
RCVD

本纳入仕様书共 8 页

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纳入仕様书改定履历 MODIFY HISTORY OF SPECIFICATION

Ver.	DATE	CONTENT	APPROVED
1.0	2016.09.13	初稿 Constitute	梁启新
1.1	2019.10.18	更新电性曲线 Update Electrical Curve	付迎华

## 目录 CATALOG

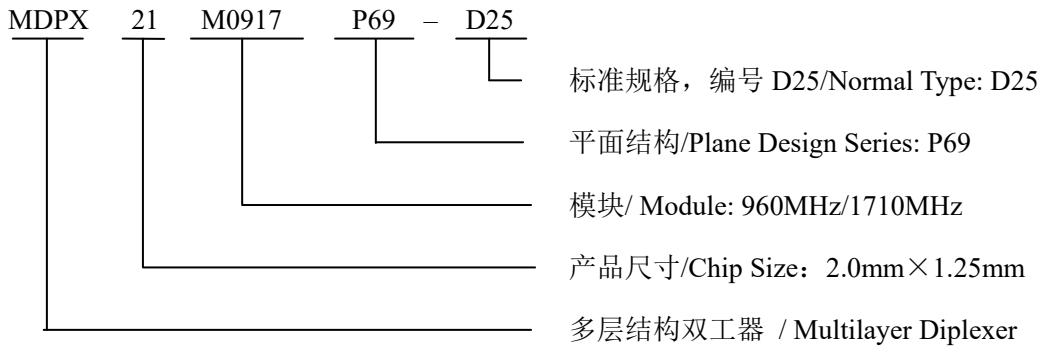
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## 1 适用范围 Scope

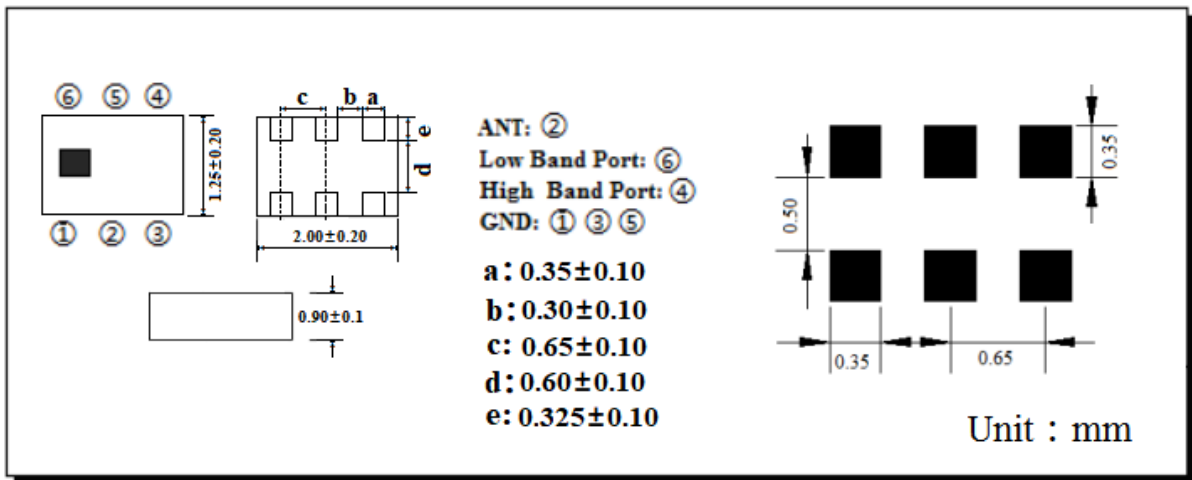
麦捷 Diplexer (MDPX 系列) 产品设计用于 PHS、WLAN、GSM、Bluetooth、PDA 和无绳电话机中, 具有低的插入损耗、高的衰减和小体积 SMD 片式设计, 能减少复杂的调校工作, 可以简化电路设计。

“Microgate” Microwave Diplexer series are designed to be used in PHS, WLAN, GSM, Bluetooth, PDA & Cordless phones with low insertion loss and high attenuation as well as small size SMD chip design, which can simplify your complex tuning and circuit design.

## 2 品名构成 Product Identification



## 3 形状、尺寸和材料 Appearance, Dimensions and Material



Part Name 名称	Structure and Material 结构及材料
Resonator 谐振体	Dielectric Material LTCC 介质材料
In/Output Terminals 输入/输出	Ag 银
Ground Base 接地面	Ag 银

## 4 测试条件 Testing Conditions

除非另有规定，否则在以下条件下测试 <Unless otherwise specified>

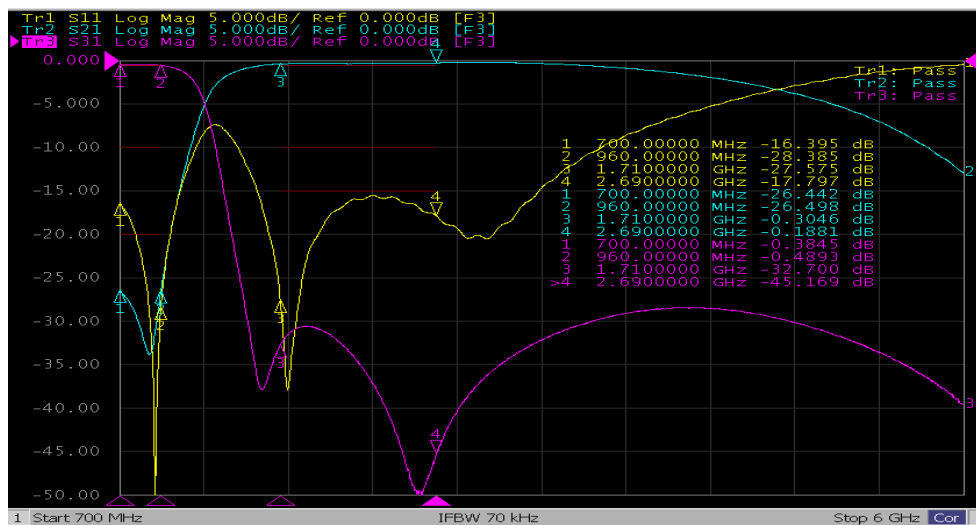
温度 Temperature : Ordinary Temperature (-40 to +85°C)  
 湿度 Humidity : Ordinary Humidity (25 to 85% RH)  
 大气压强 Atmospheric Pressure : 86 to 106 kPa

## 5 电气性能 Electrical Characteristics

操作温度范围 Operating Temperature Range : -40 to +85°C

保存温度范围 Storage Temperature Range : -40 to +85°C

No.	Item (项目)	Frequency (MHz)	Specifications (特性)
5.1	Insertion Loss (in f1) 插入衰耗	698~960 MHz	≤0.55dB
5.2	Insertion Loss (in f2) 插入衰耗	1710~2690 MHz	≤0.65dB
5.3	V.S.W.R (in BW) 驻波比 (in f1 & f2)	698~960 MHz	≤2.0
		1710~2690 MHz	
5.4	Attenuation 阻带衰耗 (in f1)	1710~2690MHz	≥13dB
5.5	Attenuation 阻带衰耗 (in f2)	698~960MHz	≥19 dB
5.6	Isolation 隔离度 (in f1)	1710~2690MHz	≥13dB
5.7	Isolation 隔离度 (in f2)	698~960MHz	≥19dB
5.8	In/Output Impedance 输入/输出阻抗		50 Ω
5.9	Power Capacity 功率容量		4W Max.



## 6 焊接条件 Recommended Soldering Conditions

### 1、焊剂 Flux, Solder

① 使用松香助焊剂，禁止使用卤化物含量超过 0.2wt% 的强酸性助焊剂。

Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).

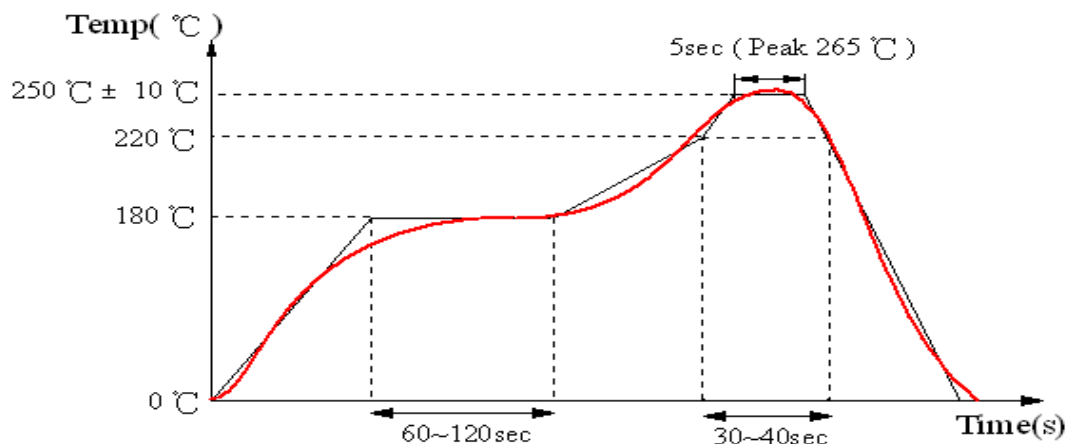
② 使用纯锡焊料 Use Sn solder.

### 2、回流焊条件 Reflow soldering conditions

● 预热时，产品表温与焊料温度的温差最大不允许超出 150℃，焊接完后冷却时，产品表温与溶剂温度之间的温差最大不允许超出 100℃。预热不足有可能引发产品表面裂纹，导致产品品质下降。

Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150℃ max. Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100℃ max. Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.

● 标准回流焊曲线 Standard soldering profile.



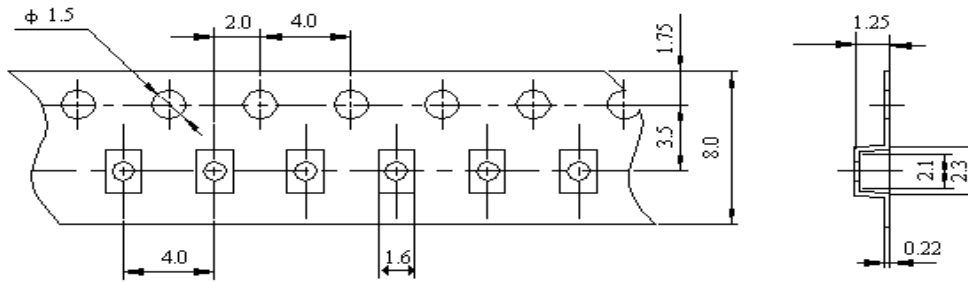
### 3、手工返工 Reworking with soldering iron

当使用电烙铁进行手工焊接时，以下条件必须严格遵守 The following conditions must be strictly followed when using a soldering iron.

预热 Pre-heating	150°C, 1 minute
尖端温度 Tip temperature	350°C max
输出功率 Soldering iron output	80w max
电烙铁头尖端尺寸 End of soldering iron	φ3mm max
焊接时间 Soldering time	3 seconds max

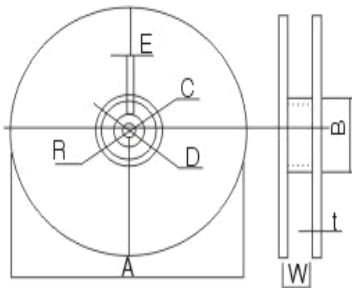
## 7 包装 Packaging

### ① 编带尺寸 Dimensions of Tape:



### ② 带轮尺寸 Dimensions of Reel

Unit: mm



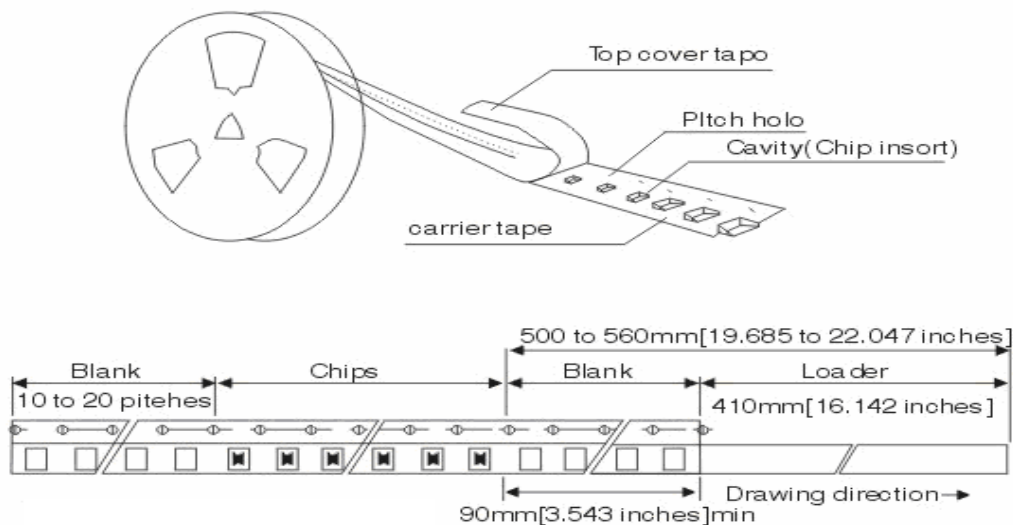
Reel material: PS (Polystyrene)

A	178±2
B	60±2
C	13.0±0.5
D	21.0±0.8
E	2.0±0.5
W	8.5±1.0
t	1.2±0.2
R	1.0±0.25

### ③ 编带抗拉强度 Pulling strength of tapes:

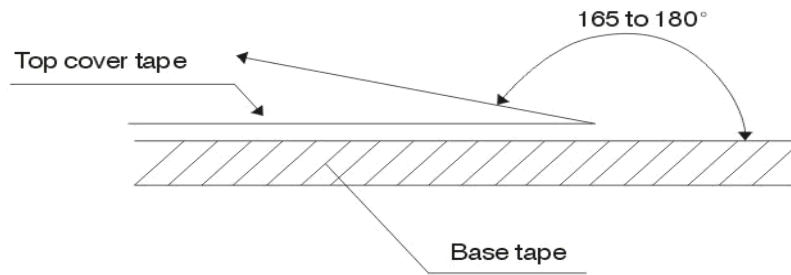
载带 Carrier tape	10N or more (1kgf or more)
上盖带 Cover tape	5N or more (1kgf or more)

### ④ 编带简图及拉伸方向 Taping figure and drawing direction:



⑤ 盖带的剥离强度 Peeling strength of cover tape:

盖带 Cover tape	0.3~0.7N (30gf~70gf)
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测试条件

- 1) 剥离角度 peel angle: 165°~180° vs. carrier tape.
- 2) 剥离速度 peel speed: 300mm/min±10%.

⑥ 包装数量 Packaging quantities: 3000 PCS / Reel